

RESERVOIR STENCIL WITH RELIEF AREAS

Abstract of the Disclosure

A stencil comprising two or more layers is disclosed for applying surface mount materials onto printed circuit boards, flexible circuits, wafers or other substrates. The stencil can accommodate preexisting surface mount components and materials. The stencil utilizes material reservoirs, relief areas and delivery apertures and can be used for depositing surface mount materials such as adhesives, conductive glues, solder paste and solder balls.

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